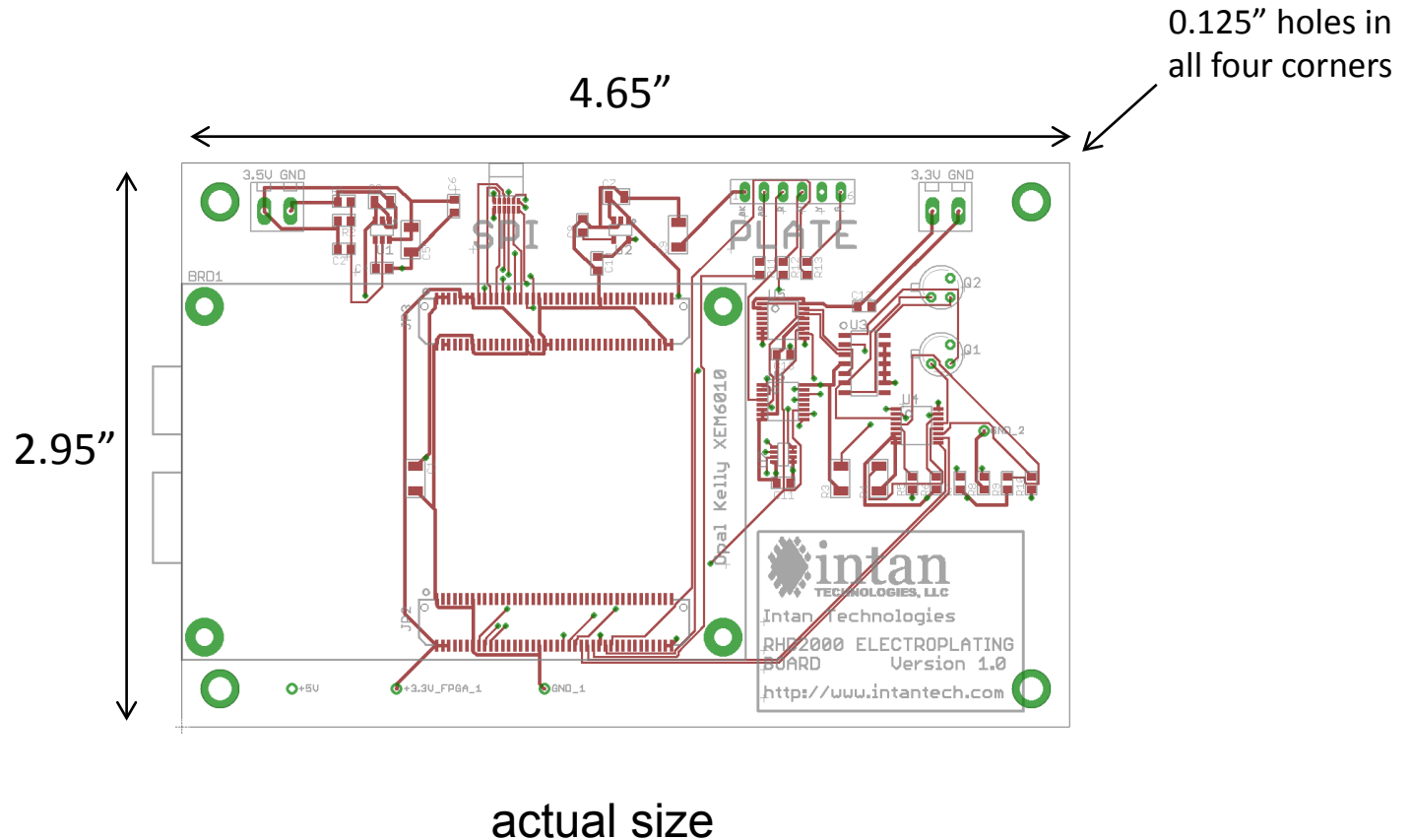# RHD2000 Plating Board

FR-4, 0.062" thick, gold immersion finish

Through-hole components and SMDs (no smaller than 0603) on **top side only**
(see BOM for details)

0.125" holes in
all four corners

4.65"

2.95"

actual size

SMD Components (36 total)

Omnetics A79623

3.5V GND

30.1 kΩ (1%)
56.0 kΩ (1%)

1 µF

100 nF

1 µF

3.3V GND

TPS79301

15 pF

10 nF

22 µF

10 nF

100 nF

22 µF

TPS79333

100 nF

100 Ω

PLATE

SPI

BRD1

Samtec BTE-040-01

74HC4053

74HC4053

100 nF

AD5662

OPA4170

U3

100 nF

Q2

Q1

GND_2

74HC4052

22 µF

Oral Kelly XEM6010

Samtec BTE-040-01

100 nF

100 MΩ (1%)
100 MΩ (1%)
10.0 MΩ (1%)
10.0 MΩ (1%)
1.00 MΩ (1%)
1.00 MΩ (1%)
100 kΩ (1%)
100 kΩ (1%)

intan
TECHNOLOGIES, LLC

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RHD2000 ELECTROPLATING
BOARD   Version 1.0

http://www.intantech.com

+5V

+3.3V_FPGA_1

GND_1

Through-Hole Components (4 total)
Place terminal blocks with openings towards outside edge of board